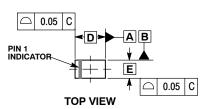
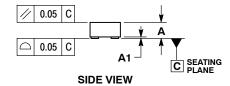
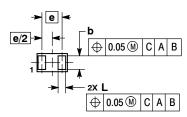


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**DATE 03 JUN 2016** 

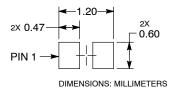






**BOTTOM VIEW** 

### **RECOMMENDED SOLDER FOOTPRINT\***



See Application Note AND8398/D for more mounting details

- NOTES:
  1. DIMENSIONING AND TOLERANCING PER
- ASME Y14.5M, 1994.
  2. CONTROLLING DIMENSION: MILLIMETERS.

	MILLIMETERS		
DIM	MIN	MAX	
Α	0.25	0.31	
A1		0.05	
b	0.45	0.55	
D	1.00 BSC		
Е	0.60 BSC		
е	0.65 BSC		
Ĺ	0.20	0.30	

#### **GENERIC MARKING DIAGRAM1\***

## **GENERIC MARKING DIAGRAM2\***





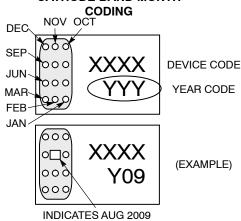
XXXX = Specific Device Code YYY = Year Code

XX = Specific Device Code

M = Date Code

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G", may or not be present.

# **CATHODE BAND MONTH**



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<sup>\*</sup>For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.